

**AMENDMENTS TO THE CLAIMS**

1 – 6. (Cancelled)

7. (Original) A polishing composition for a substrate for memory hard disk comprising an abrasive in an aqueous medium, wherein the abrasive comprises silica particles having particle sizes of from 5 to 120 nm in an amount of 50% by volume or more, wherein the abrasive comprises:

(i) 10 to 70% by volume of small size silica particles having particle sizes of 5 nm or more and less than 40 nm based on an entire amount of the silica particles having particle sizes of from 5 to 120 nm;

(ii) 20 to 70% by volume of intermediate size silica particles having particle sizes of 40 nm or more and less than 80 nm based on an entire amount of the silica particles having particle sizes of from 5 to 120 nm; and

(iii) 0.1 to 40% by volume of large size silica particles having particle sizes of 80 nm or more and 120 nm or less based on an entire amount of the silica particles having particle sizes of from 5 to 120 nm.

8. (Previously Presented) A polishing composition for a substrate for memory hard disk comprising an abrasive in an aqueous medium, wherein the abrasive comprises silica particles having particle sizes of from 5 to 120 nm in an amount of 50% by volume or more, wherein the abrasive comprises:

(i) 5 to 70% by volume of small size silica particles having particle sizes of from 10 to 30 nm based on an entire amount of the silica particles having particle sizes of from 5 to 120 nm;

(ii) 20 to 70% by volume of intermediate size silica particles having particle sizes of from 45 to 75 nm based on an entire amount of the silica particles having particle sizes of from 5 to 120 nm; and

(iii) 0.1 to 25% by volume of large size silica particles having particle sizes of from 90 to 110 nm based on an entire amount of the silica particles having particle sizes of from 5 to 120 nm.

9. (Original) The polishing composition according to claim 7, wherein the silica particles are colloidal silica particles.

10. (Original) The polishing composition according to claim 8, wherein the silica particles are colloidal silica particles.

11. (Original) The polishing composition according to claim 7, further comprising at least one member selected from the group consisting of acids, salts thereof and oxidizing agents.

12. (Original) The polishing composition according to claim 7, wherein a pH thereof is from 1 to 4.5.

13. (Withdrawn ) A polishing process for a substrate for memory hard disk with suppressed generation of carrier squeals, comprising the step of polishing a substrate for memory hard disk with the polishing composition of claim 8.

14. ( Currently Amended) A method of reducing micropits of a substrate, comprising the step of polishing a substrate to be polished with ~~applying~~ the polishing composition of claim 7 ~~to a substrate to be polished.~~

15. (Withdrawn) A method for manufacturing a substrate for memory hard disk, comprising the step of polishing an Ni--P plated substrate for memory hard disk with the polishing composition of claim 8.

16. (Withdrawn) A method for manufacturing a substrate for memory hard disk, comprising the step of polishing an Ni--P plated substrate for memory hard disk with the polishing composition of claim 7.

17-18. (Cancelled)